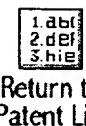


PatentWeb
HomeEdit
SearchReturn to
Patent List

Help

 Include in patent order

MicroPatent® Worldwide PatSearch: Record 1 of 1

[no drawing available]

Family Lookup**JP63194983****THERMALLY FUSIBLE HEAT-SENSITIVE TRANSFER SHEET**

IWASAKI TSUNEO

Inventor(s): ;OKABE TAKAYUKI

Application No. 62028588 , Filed 19870210 , Published 19880812

Abstract:

PURPOSE: To lower a surface tension of ink, to suppress noise during transfer operation and to improve resolution of printing by providing a transfer layer wherein thermally fusible ink is applied onto one face of supporting material, and incorporating thermoplastic resin having a specific softening temperature and silicone surfactant which is in liquid state at a specific temperature in the thermally fusible ink.

CONSTITUTION: In a thermally fusible transfer sheet having supporting material and a transfer layer formed by applying thermally fusible ink onto one face of the supporting material, the ink contains viscous thermoplastic resin having softening temperature of 50W120°C and silicone surfactant which is in liquid state at the temperature of at least 15W50°C. Supporting material includes film or paper. Thermoplastic resin includes ethylcellulose, polyester resin, petroleum resin, ethylene-vinyl acetate copolymer, etc. having high compatibility with binder and coloring agent and proper viscosity. Non-ionic silicone surfactant having hydrophobic group composed of dimethyl silicone oil and hydrophilic group composed of polyether is employed.

COPYRIGHT: (C)1988,JPO&Japio

Int'l Class: B41M00526**MicroPatent Reference Number:** 000247392

COPYRIGHT: (C) JPO

PatentWeb
HomeEdit
SearchReturn to
Patent List

Help

For further information, please contact:
Technical Support | Billing | Sales | General Information